

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the present application.

Listing of Claims:

Claim 1 (currently amended): A wafer holder for semiconductor manufacturing equipment, the wafer holder having a wafer-carrying surface and characterized in that the diameter **a** of the wafer holder wafer-carrying surface is not greater than the diameter **b** of the wafer holder surface on its side opposite the wafer-carrying surface, wherein the diameter **b** minus the diameter **a** is greater than 0 μm and less than or equal to 35 mm.

Claim 2 (currently amended): The wafer holder set forth in claim 1, wherein the diameter **b** is larger than minus the diameter **a** by 50 μm or more is in the range from 50 μm to 35 mm.

Claim 3 (original): The wafer holder set forth in claim 1, being a ceramic susceptor interiorly in or superficially on which a resistive heating element is formed.

Claim 4 (original): The wafer holder set forth in claim 2, being a ceramic susceptor interiorly in or superficially on which a resistive heating element is formed.

Claim 5 (original): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 1 is installed.

Claim 6 (original): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 2 is installed.

Claim 7 (original): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 3 is installed.

Claim 8 (original): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 4 is installed.

Claim 9 (new): The wafer holder set forth in claim 1, wherein the diameter **b** minus the diameter **a** is greater than 10 mm and less than 30 mm.

Claim 10 (new): The wafer holder set forth in claim 1, wherein the diameter **b** is within the range from 100.02 to 110% of the diameter **a**.

Claim 11 (new): The wafer holder set forth in claim 1, wherein the diameter **b** is within the range from 100.3 to 110% of the diameter **a**.

Claim 12 (new): The wafer holder set forth in claim 1, wherein the diameter **b** is within the range from 103 to 109% of the diameter **a**.